

Electronic Acknowledgement Receipt

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Application Number:	10763859
Confirmation Number:	8528
Title of Invention:	SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS
First Named Inventor:	Tae Heon Lee
Customer Number:	7663
Filer:	Mark B. Garred/Andrea Levine
Filer Authorized By:	Mark B. Garred
Attorney Docket Number:	AMKOR-053G
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment after Notice of Allowance (Rule 312)	amendafterallowwithexhibts.pdf	524402	no	18

Warnings:**Information:****Total Files Size (in bytes):**

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.